

This thin borosilicate glass is the gold standard in imaging and sensing fields. Thanks to unique down-draw technologies, D 263° T eco has a fire-polished surface, high optical precision and geometrical accuracy. It is available in a variety of thicknesses from 1.1 mm down to 0.03 mm.







Wide thickness range



**High chemical** resistance



**Tight geometrical** properties



Fire-polished surface with low roughness



**High temperature** stability

### **Applications**

All-round technical excellence makes D 263° T eco a highly valued glass in many applications across different fields, setting gold standards in these markets.

D 263® T eco can be used for:

- · IR cut filter
- Optical low pass filter (OLPF) substrate
- Wafer-level optics
- Micro-lens arrays (MLA)
- Diffractive optical elements (DOE)
- Diffusors
- Sensor cover
- Carrier wafer



Automotive





Consumer electronics



Smart home



**Optics** 



Semiconductors



Industry



# SCHOTT D 263® T eco

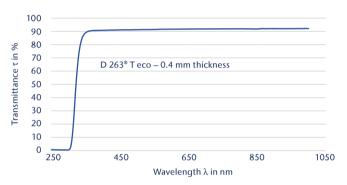
## Outstanding and adaptable technical advantages

#### High optical transmittance

The unique composition of D 263° T eco and its top-quality blend of raw materials enables a high level of high optical transmittance in the UV to NIR range. A colorless appearance also helps to deliver optimum image quality, without unwanted colorization effects regardless of application.

#### High chemical stability

SCHOTT D 263° T eco performs consistently well in demanding conditions. Its high chemical resistance makes it particularly resilient in the consumer electronics, semiconductor, automotive and optical fields.



Optical properties		
Refractive index n <sub>D</sub>	1.5230	
Luminous transmittance $\tau_{vD65}$ (d = 0.30 mm)	91.7%	

Chemical properties			
Hydrolytic resistance	<b>DIN ISO 719</b>	HGB 1	
Acid resistance	DIN 12116	S 3	
Alkali resistance	DIN ISO 695	A 2	

#### A wide range thicknesses

While D 263° T eco is available in a wide variety of thicknesses (from 0.03 mm to 1.1 mm), the geometrical tolerances of the glass remain consistently tight, with guaranteed quality for sheet, cut-to-size substrates and wafer.

#### **Tight geometrical properties**

Tight thickness tolerance, low TTV and warp enables high quality wafer level optics.

Mechanical properties		
Density ρ	g/cm³	2.51
Young's modulus E	kN/mm²	72.9
Poisson's ratio µ		0.21
Knoop hardness	HK 0.1/20	470
Vickers hardness	HV 0.2/25	510
Chemical toughening		possible

Electrical properties			
Dielectric constant $\epsilon_{r}$	1 GHz	6.4	
	5 GHz	6.3	
Dissipation factor tan $\delta$ in $10^{-4}$	1 GHz	74	
	5 GHz	101	

Thermal properties	
Coefficient of thermal expansion $\alpha$ (20 °C; 300 °C)	7.2 · 10 <sup>-6</sup> K <sup>-1</sup>
Transformation temperature T <sub>q</sub>	557°C

glass made of ideas

Geometrical properties	Sheet			Wafer	
Formats*	Min. Length x Width [mm]	440 x 360		Rectangular min.	50 x 50
	Max. Length x Width [mm]	510 x 430		Rectangular max.	300 x 300
				Round min.	50 (2 inch)
				Round max.	300 (12 inch)
Thickness range	Min. [mm]		0.03		
	Max. [mm]		1.10		
Surface roughness			< 1 nm RM	S	

<sup>\*</sup> Customized formats are available upon request.





